micro dispensing in perfection!

1 µl ±1%



preeflow® 1K dispensers

The brand with the systematic approach. preeflow[®] - high-quality products ranging from control units to dispensers that live up to our vision 'small, precise, economical'.

> eco-PEN600 min. dosing quantity 0.015 ml volume flow 1.4-16.0 ml/min

> > weight

approx. 750 g

eco-PEN300

min. dosing quantity 0.001 ml volume flow 0.12-1.48 ml/min weight approx. 380 g

eco-PEN450

min. dosing quantity 0.004 ml volume flow 0.5-6.0 ml/min weight approx. 410 g

reeflow[®] eco-PEN300

IOW® eco-PEN450

•

OW[®] eco-PEN600

0

eco-PEN700^{3D} min. dosing quantity 0.060 ml volume flow 5.30-60.0 ml/min weight approx. 750 g

preeflow® 1K controllers

EC200-K

CO-CONTROL -

Make in Company O

plug'n'dose

Plug 'n' Dorte



preeflow"



preeflow® 2K dispensers

0

eco DUO

4-009

preeflow® eco-PEN600

_{eco} 🖲 DUO

eco-DUO450

DW® eco.PEN450

min. dosing quantity 0.010 ml volume flow 0.2-12.0 ml/min weight approx. 1,100 g

eco-DUO600

min. dosing quantity 0.030 ml volume flow 0.6-32.0 ml/min weight approx. 1,600 g

Precision mechanics coupled with the latest digital control - a perfect combination. Designed to optimize your 2K process. preeflow[®] - Microdispensing in perfection!

preeflow[®] 2K controllers



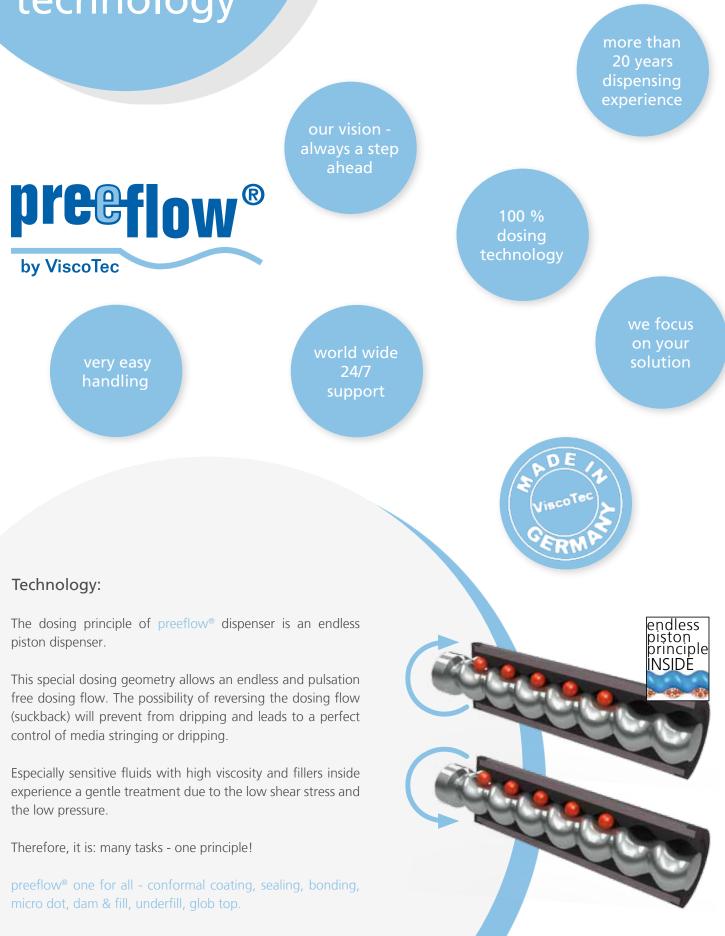


plugʻnʻmix

You can find more information about our 2K equipment and the other preeflow[®] products on our website: www.preeflow.com

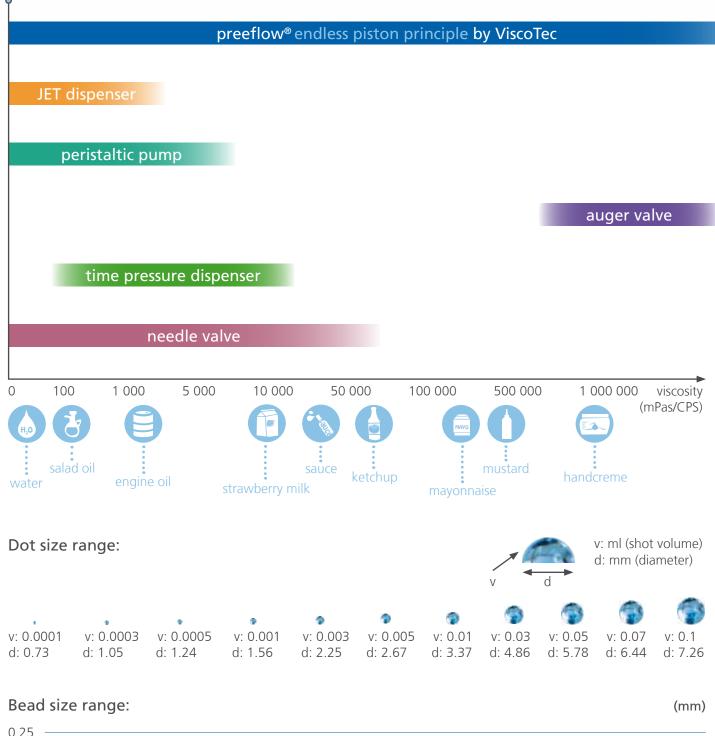
benefits and technology

The medium is unaltered by this process. And simply by switching to reverse-flow, preeflow[®] ensures a clean and controlled stop of material or medium. No drips, no mess - always!





Dosing technologies in use:



0.20	
05	
0.5	
1 0	
1.0	
15	
1.5	
20	
2.0	
2.5	
3.0	
0.0	

applications in focus

preeflow[®] products offer the ideal properties to ensure that all relevant 1 & 2 component applications in several industries are perfectly dosed!

> max. particle size 1 mm

endless piston principle inside

Bonding

In the industrial world, the term of Bonding refers to join securely to something else, especially by means of an adhesive or chemical substance, heat or pressure. In our case, any combination of any type and roughness of materials could be joined together through the application of adhesives. The bonding therefore replaces more traditional technics such as riveting or welding.

easy to integrate in machines

high repeatability more than 99 %

> reversible material flow

Optical Bonding

Optical Bonding is a process in which a clear adhesive is applied between the layers of glass in a touch screen display. The main goal of this bonding process is to improve the performance of the display when outdoors. This procedure eliminates the gap between the glass and the display. A great deal of importance is placed on dosing precision in the field of smartphone and tablet manufacturing in particular.

Conformal Coating

A Conformal Coating is a protective coating which takes the form of a non-transparent or transparent varnish that is applied to all or parts of PCBs. The materials are usually high viscosity thermal or UV curing materials and are dosed onto the PCB using either a thin film or a thick film procedure.

> bead factor < 2 %

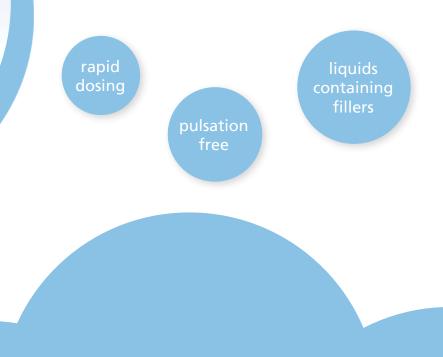
no stringing nor dripping

independent of pressure, temperature and time





In Dam & Fill applications, the primary aim is to protect highly complex assemblies. Firstly, a high viscosity barrier, known as the "Dam", is applied to the surface to be sealed. Then the adjacent area is filled with a filler which provides protection and sealing effect.



Glob Top

Glob Top potting is designed to protect sensitive components, usually semiconductor chips, from mechanical stress such as vibrations or fluctuations in temperature. External environmental factors too, like moisture or corrosion, are thus prevented from having an impact on the potted components. This effect is realised by applying a fluid resin matrix, mostly an epoxy resin adhesive, which is then cured.

gentle product handling reproductible results

> pure volumetric dosing

Underfill

easy to clean

Underfill applications usually are used with isotropic conductive adhesives. In this case, the isotropic conductive adhesive provides the electrical connection from the microchip to the substrate. As this adhesive is not applied over the entire surface, after the thermally or UV curing process, another filling of the hollow space is necessary, the so called "Underfill".

up to three shots per second exact volume control

2K epoxy

heat curing

gasoline

examples of materials UV & light curing

anaerobic

1K epoxy

shear-sensitive adhesives

flavours

LED resins

thermal conductive paste

high fill fluids

sealing agents

toluene

short and easily accessible fluid path

> self sealing displacement system

Micro Dispensing

Micro Dispensing refers to the dosing of fluid media in volume of just a few microlitres. Other fields of application are, for example, bead dosing, sealing, dot dosing, potting and 2 component applications. These applications in particular call for high levels of precision, repeat accuracy and reliability.

press stab

> dosing accuracy + 1 %

Encapsulating

Encapsulating is the process of applying a fluid sealing compound to a small and define area on a component or on a surface. The sealing compound protects the electrical component both in transports and from environmental influences such as vibration, shakes, humidity, dust and extreme temperature.

Other benefits include an improved electrical insulation, a higher safety against damage as well as a better chemical resistance.

			alcohol	grease		
solder paste			MEK	thermal grease		
RTV rubbers	isopropan	nol	brazing paste		PU	
silver paste		paints & ir	nks		and	
flux	cosmetics & medicines	acetone	primer		many	
industrial oils		epoxy resin				
porfumo	biotechnical suspensions electro		rolytic solutions		more	
perfume						







ViscoTec Pumpen- u. Dosiertechnik GmbH Amperstr. 13 | 84513 Töging a. Inn | Germany Specialized dealer:

E-Mail: mail@viscotec.de Internet: www.viscotec.de Telefon: +49(0)8631/9274-0 Fax: +49(0)8631/9274-300 ViscoTec